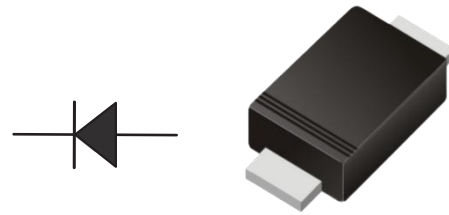


Surface Mount General Purpose Silicon Rectifiers

Parameter	Value	Unit
V_{RRM}	50~1000	V
$I_{F(AV)}$	2.0	A



S2MBF

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place

Applications

- For use in general purpose rectification in power supplies, inverters, converters, and as freewheeling diodes for consumer and telecommunications applications.

Absolute Maximum Ratings and Characteristics (Ta=25°C unless otherwise noted)

Parameter	Symbol	S2ABF	S2BBF	S2DBF	S2GBF	S2JBF	S2KBF	S2MBF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_C=125^\circ\text{C}$	$I_{F(AV)}$	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	55							A
Maximum Instantaneous Forward Voltage at 2A	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	5 100							μA
Typical Junction Capacitance (1)	C_j	25							pF
Typical Thermal Resistance (2)	$R_{\theta JA}$ $R_{\theta JC}$	60 18							$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

(1) Measured at 1 MHz and applied reverse voltage of 4 VD.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Typical characteristics

Fig.1 Forward Current Derating Curve

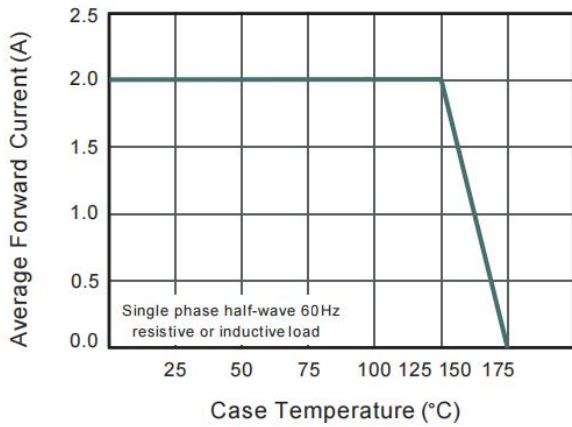


Fig.2 Typical Reverse Characteristics

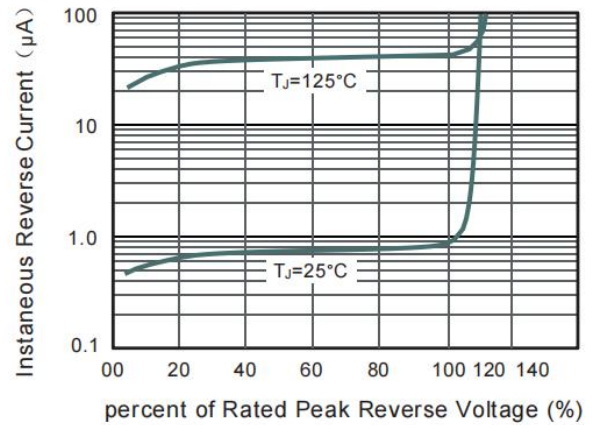


Fig.3 Typical Forward Characteristic

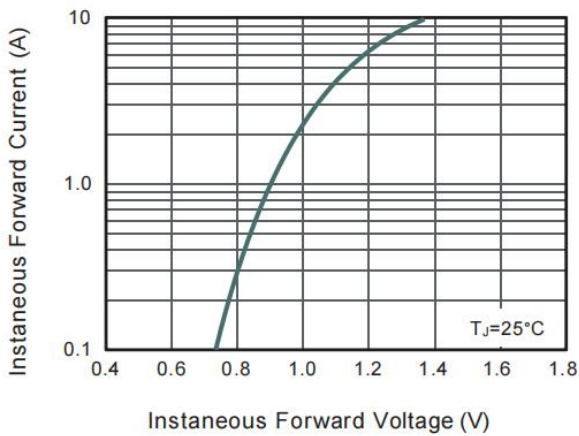


Fig.4 Typical Junction Capacitance

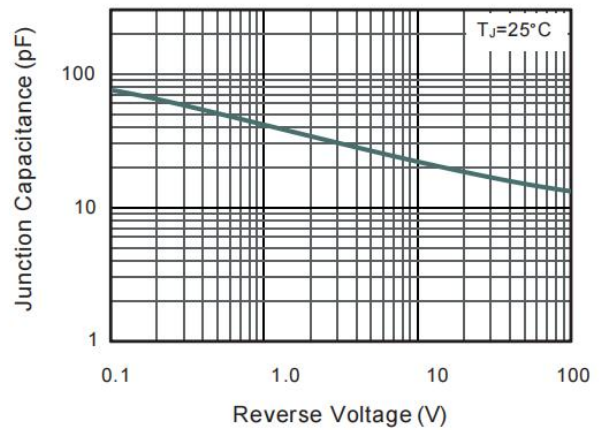
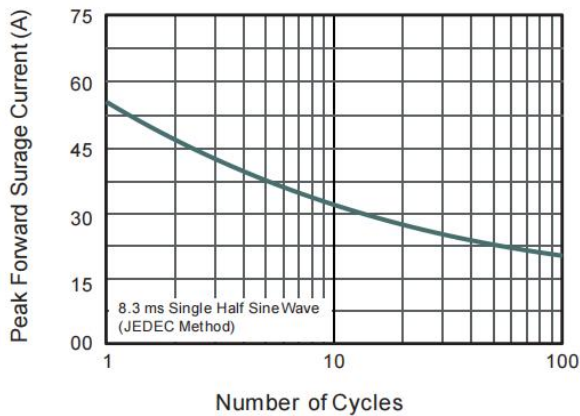
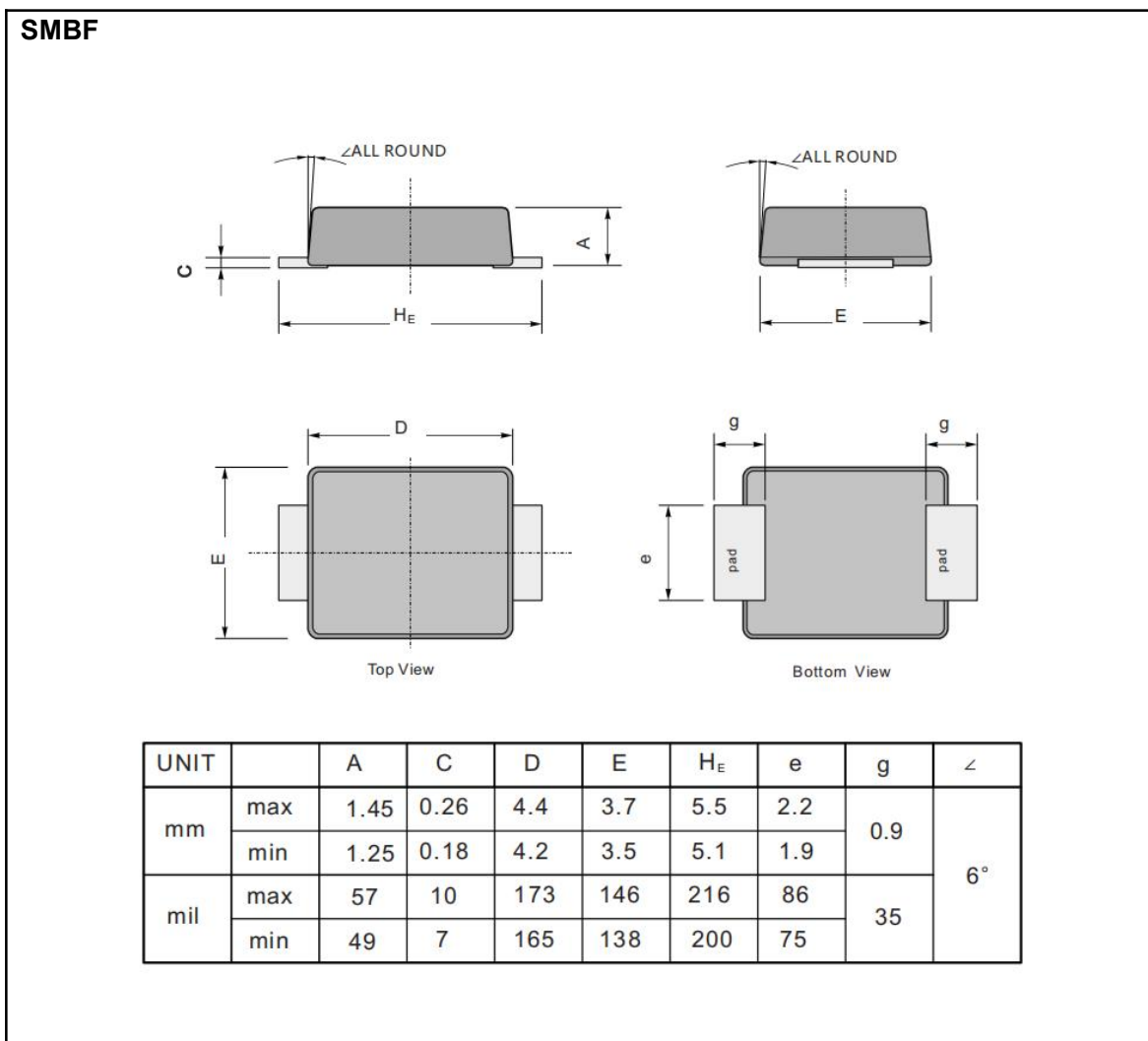


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

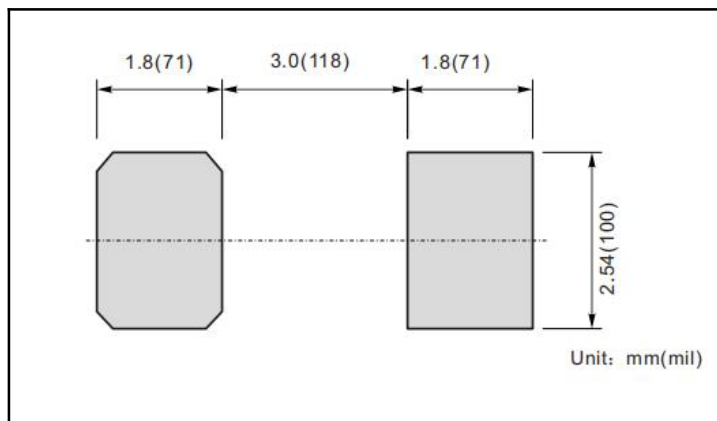


Package Outlines

Plastic surface mounted package; 2 leads



The recommended mounting pad size



Marking

Type number	Marking code
S2ABF	S2AB
S2BBF	S2BB
S2DBF	S2DB
S2GBF	S2GB
S2JBF	S2JB
S2KBF	S2KB
S2MBF	S2MB

***Important Usage Information and Disclaimer**

The specifications of Zhuhai Hypersemi Co., Ltd. products are not guarantees of product characteristics. They reflect typical performance expected in standard applications, which may vary with specific uses. Users must conduct prior testing for their applications and make necessary adjustments.

Users are responsible for the safety of applications utilizing our products and must implement adequate safety measures to prevent physical injury, fire, or other risks in case of product failure. It is the user's duty to ensure that application designs comply with all applicable laws and standards. Our products must not be used in any applications where a product failure could reasonably result in personal injury, unless specifically authorized in a signed document by Zhuhai Hypersemi Co., Ltd.

No representations or warranties are made regarding the accuracy or completeness of this information, including any claims of non-infringement of third-party intellectual property rights. Zhuhai Hypersemi Co., Ltd. assumes no liability for any applications or uses of its products and does not grant any licenses to its intellectual property rights or those of others. We also make no claims regarding non-infringement of third-party intellectual property rights that may arise from applications.

Due to technical requirements, our products may contain hazardous substances. For details, please contact your nearest sales office. This document replaces all previous information and may be updated. We reserve the right to make changes.